

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-12 (Canceled).

Claim 13 (Previously Presented): A method to produce conductive rods on an electronic component comprising one or more conductive blocks, each of the conductive rods being in at least partial contact with a block of the electronic component, the method comprising:

deposition of a conductive base on the component;

deposition of a masking layer on the conductive base;

formation in the masking layer of a plurality of holes, at least one conductive block of the conductive blocks being located opposite one or more holes, at least one hole of the holes having none of the conductive blocks opposite it;

etching the conductive base via the holes;

filling of the holes with a conductive material base, by electrolysis and using the conductive base as an electrode, to form the conductive rods; and

removal of the masking layer.

Claim 14 (Canceled).

Claim 15 (Previously Presented): A method according to claim 13, the masking layer comprising at least one photosensitive polymer layer.

Claim 16 (Previously Presented): A method according to claim 13, wherein the conductive blocks are inserted in a passivation layer coating the electronic components.

Claim 17 (Previously Presented): A method according to claim 13, the conductive base being formed from a stack of at least two different conductive layers.

Claim 18 (Previously Presented): A method according to claim 13, further comprising, after the masking layer removal, an at least partial conductive base removal or selective conductive base etching.

Claim 19 (Previously Presented): A method according to claim 13, further comprising, after the filling by electrolysis, an additional noble metal-based chemical deposition on the conductive rods.

Claim 20 (Currently Amended): [[A]] The method of claim 13, wherein the electronic component is a microelectronic device obtained by the method according to claim 13,

Claims 21-36 (Canceled).

Claim 37 (Currently Amended): A method to produce conductive rods on an electronic component including one or more conductive blocks, each of the conductive rods being in at least partial contact with a block of the electronic component, the method comprising:

deposition of a conductive base on the component;  
deposition of a thin insulating layer on the conductive base;

formation of a plurality of openings in the thin insulating ~~later~~ layer, each opening being located opposite a conductive block;

deposition of a masking layer on the conductive base;

formation in the masking layer of a plurality of holes, at least one conductive block of the conductive blocks being located opposite one or more holes, at least one hole of the holes having none of the conductive blocks opposite it;

filling of the holes with a conductive material base, by electrolysis and using the conductive base as an electrode, to form the conductive rods; and

removal of the masking layer.

Claim 38 (Previously Presented): A method according to claim 37, the masking layer comprising at least one photosensitive polymer layer.

Claim 39 (Previously Presented): A method according to claim 37, wherein the conductive blocks are inserted in a passivation layer coating the electronic components.

Claim 40 (Previously Presented): A method according to claim 37, the conductive base being formed from a stack of at least two different conductive layers.

Claim 41 (Previously Presented): A method according to claim 37, further comprising, after the masking layer removal, an at least partial conductive base removal or selective conductive base etching.

Claim 42 (Previously Presented): A method according to claim 37, further comprising, after the filling by electrolysis, an additional noble metal-based chemical deposition on the conductive rods.

Claim 43 (Currently Amended): [[A]] The method of claim 37, wherein the electronic component is a microelectronic device obtained by the method according to claim 37.

Claim 44 (Previously Presented): A method according to claim 37, wherein, of the plurality of holes formed in the hole formation in the masking layer, some holes reveal the thin insulating layer, and some other holes reveal the conductive base.